## AM7433P-T1-PF-VB Datasheet P-Channel 30 V (D-S) MOSFET

#### **PRODUCT SUMMARY**

 $R_{DS(on)}(\Omega)$ 

#### **FEATURES**

- Extended V<sub>GS</sub> range (± 25 V) for adaptor switch applications
- Extremely low R<sub>DS(on)</sub>
- Trench Power MOSFET
- 100 % R<sub>g</sub> and UIS Tested

- a. Based on T<sub>C</sub> = 25 °C.
  b. Surface mounted on 1" x 1" FR4 board.
- d. Maximum under steady state conditions is 90 °C/W.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static				<u>'</u>			
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 30			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J 250 A		- 24		mV/°C	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = - 250 μA		6			
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_{D} = -250 \mu A$	- 1.0		- 2.5	V	
Coto Course Leglione	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 25 \text{ V}$			± 150		
Gate-Source Leakage		$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 15	μΑ	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$			- 1		
		V <sub>DS</sub> = - 30 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C			- 10		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> ≤ - 5 V, V <sub>GS</sub> = - 10 V	- 20			Α	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 13 A		0.0080			
		V <sub>GS</sub> = - 6 V, I <sub>D</sub> = - 10 A		0.0090		Ω	
		V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 8 A		0.0120		1	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 13 A		44		S	
Dynamic <sup>b</sup>						l	
Input Capacitance	C <sub>iss</sub>			4620		pF	
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> = - 15 V, V <sub>GS</sub> = 0 V, f = 1 MHz		880			
Reverse Transfer Capacitance	C <sub>rss</sub>			820			
Total Gate Charge	Qg	V <sub>DS</sub> = - 15 V, V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 17.3 A		102	153	53	
				66	80	nC	
Gate-Source Charge	$Q_{gs}$	$V_{DS} = -15 \text{ V}, V_{GS} = -5 \text{ V}, I_{D} = -17.3 \text{ A}$		16			
Gate-Drain Charge	$Q_{gd}$			28			
Gate Resistance	$R_g$	f = 1 MHz	0.3	1.3	2.6	Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			70	105		
Rise Time	t <sub>r</sub>	$V_{DD} = 0 \text{ V}, R_L = 1.5 \Omega$		70	105	ns	
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong$ - 10 A, $V_{GEN}$ = - 4.5 V, $R_g$ = 1 $\Omega$		45	68		
Fall Time	t <sub>f</sub>			27	41		
Turn-On Delay Time	t <sub>d(on)</sub>			18	30		
Rise Time	t <sub>r</sub>	$V_{DD}$ = - 15 V, $R_L$ = 1.5 $\Omega$		15	25		
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong$ - 10 A, $V_{GEN}$ = - 10 V, $R_g$ = 1 $\Omega$		52	80		
Fall Time	t <sub>f</sub>			14	25		
<b>Drain-Source Body Diode Characteristic</b>	s						
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			- 5.8	А	
Pulse Diode Forward Current	I <sub>SM</sub>				- 60		
Body Diode Voltage	$V_{SD}$	I <sub>S</sub> = - 10 A, V <sub>GS</sub> = 0 V		- 0.78	- 1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			35	53	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>F</sub> = - 10 A, dl/dt = 100 A/μs, T <sub>J</sub> = 25 °C		25	38	nC	
Reverse Recovery Fall Time	t <sub>a</sub>	$_{1}^{1}$ $_{1}^{1}$ $_{2}^{1}$ $_{3}^{1}$ $_{4}^{1}$ $_{5}^{1}$ $_{1}^{1}$ $_{2}^{2}$ $_{5}^{1}$ $_{6}^{1}$ $_{7}^{1}$ $_{1}^{2}$ $_{1}^{2}$ $_{2}^{2}$ $_{3}^{1}$ $_{4}^{2}$ $_{5}^{1}$ $_{1}^{2}$ $_{2}^{2}$ $_{5}^{2}$ $_{5}^{2}$ $_{6}^{2}$		19			
Reverse Recovery Rise Time	t <sub>b</sub>			ns			

#### Notes:

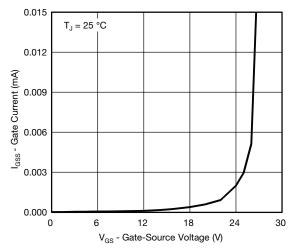
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%$ 

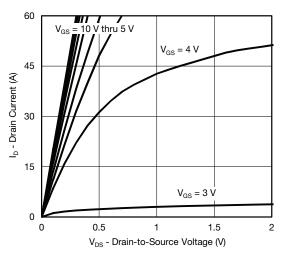
b. Guaranteed by design, not subject to production testing.



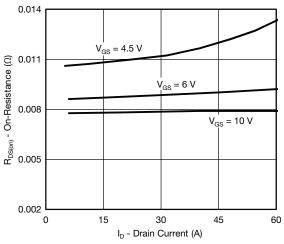
#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



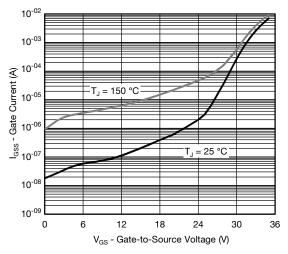
Gate Current vs. Gate-Source Voltage



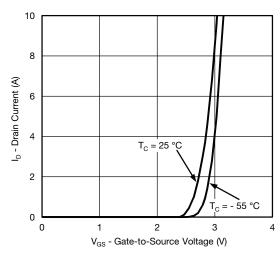
**Output Characteristics** 



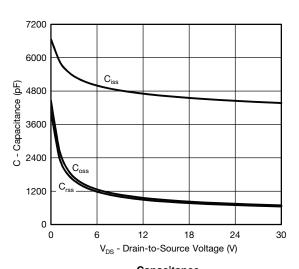
On-Resistance vs. Drain Current



Gate Current vs. Gate-Source Voltage



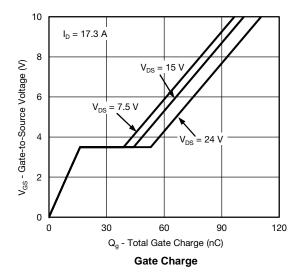
**Transfer Characteristics** 

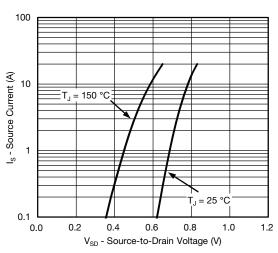


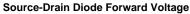
Capacitance

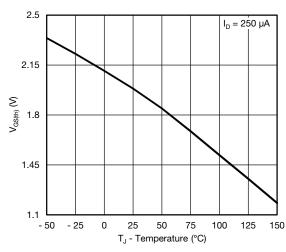


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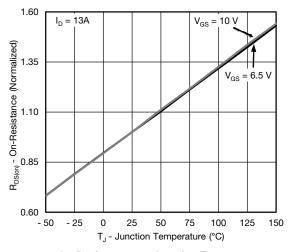




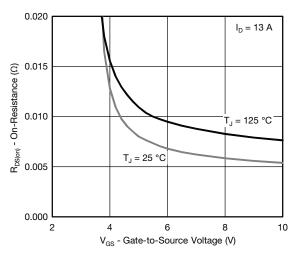




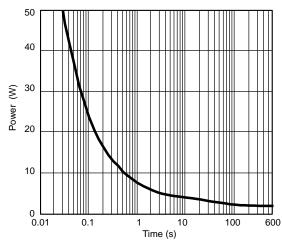
**Threshold Voltage** 



On-Resistance vs. Junction Temperature



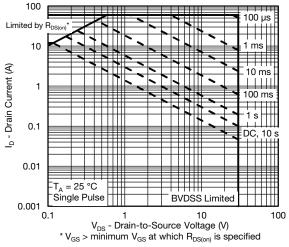
On-Resistance vs. Gate-to-Source Voltage



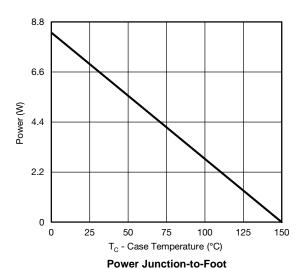
Single Pulse Power, Junction-to-Ambient

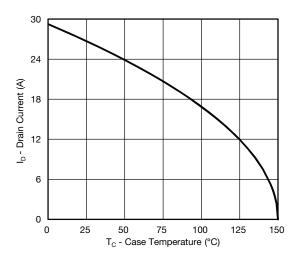


#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

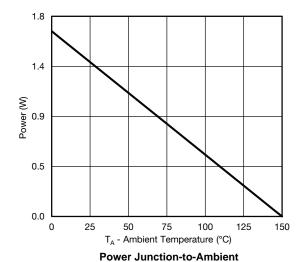










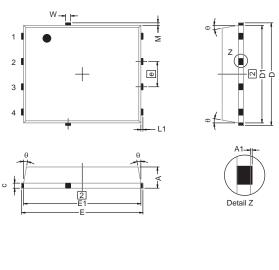


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<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max.)}$  = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

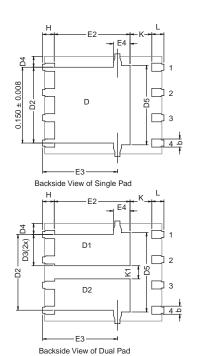


### PowerPAK SO-8, (SINGLE/DUAL)





- 1. Inch will govern.
- 2 Dimensions exclusive of mold gate burrs.
- 3. Dimensions exclusive of mold flash and cutting burrs.



	MILLIMETERS			INCHES			
DIM.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	
Α	0.97	1.04	1.12	0.038	0.041	0.044	
A1	0.00	-	0.05	0.000	-	0.002	
b	0.33	0.41	0.51	0.013	0.016	0.020	
С	0.23	0.28	0.33	0.009	0.011	0.013	
D	5.05	5.15	5.26	0.199	0.203	0.207	
D1	4.80	4.90	5.00	0.189	0.193	0.197	
D2	3.56	3.76	3.91	0.140	0.148	0.154	
D3	1.32	1.50	1.68	0.052	0.059	0.066	
D4	0.57 TYP.			0.0225 TYP.			
D5	3.98 TYP.			0.157 TYP.			
Е	6.05	6.15	6.25	0.238	0.242	0.246	
E1	5.79	5.89	5.99	0.228	0.232	0.236	
E2	3.48	3.66	3.84	0.137	0.144	0.151	
E3	3.68	3.78	3.91	0.145	0.149	0.154	
E4	0.75 TYP.			0.030 TYP.			
е	1.27 BSC			0.050 BSC			
K	1.27 TYP.			0.050 TYP.			
K1	0.56	-	-	0.022	-	-	
Н	0.51	0.61	0.71	0.020	0.024	0.028	
L	0.51	0.61	0.71	0.020	0.024	0.028	
L1	0.06	0.13	0.20	0.002	0.005	0.008	
θ	0°	-	12°	0°	-	12°	
W	0.15	0.25	0.36	0.006	0.010	0.014	
М		0.125 TYP.	1	0.005 TYP.			

DWG: 5881

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